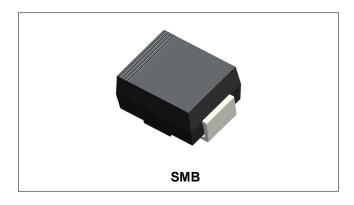






MURS360B ULTRAFAST RECTIFIER



Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- · Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching Power Supply
- Power Switching Circuits
- General Purpose

Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Characteristic	Symbol	MURS360B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Rectified Output Current (Note 1) @T _A = 55°C	lo	3.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	150	А
Forward Voltage (per element) @I _F = 3.0A	V _{FM}	1.25	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _{RM}	10 500	μΑ
Maximum Reverse Recovery Time (Note 1)	Trr	50	ns
Typical Thermal Resistance Junction to Ambient (Note 2)	R _{θJA}	25	K/W
Junction Temperature	TJ	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Note: 1. Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

2. Mount on Cu-Pad Size 16mm×16mm on P.C.B.

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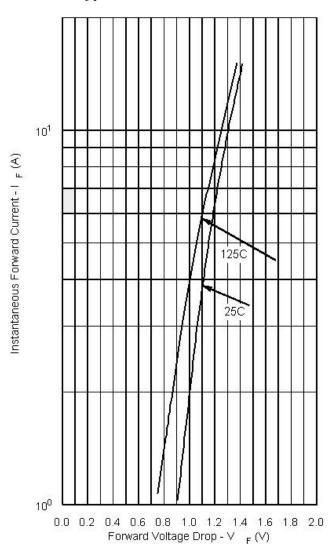




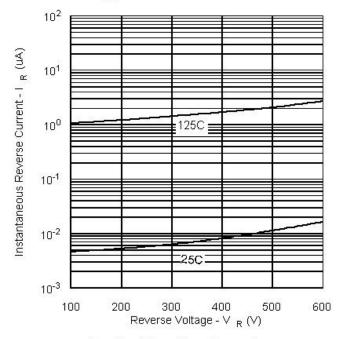


Ratings and Characteristics Curves

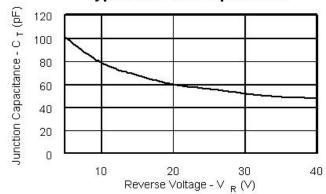
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



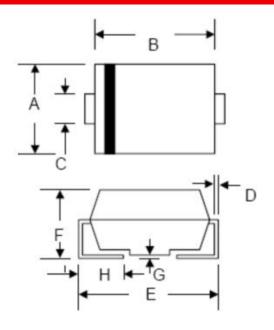
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Mechanical Dimensions SMB



CVMDOL	Millimeters		Inches	
SYMBOL	Min.	Max.	Min.	Max.
Α	3.30	3.94	0.130	0.155
В	4.06	4.70	0.160	0.185
С	1.80	2.20	0.071	0.087
D	0.152	0.305	0.006	0.012
E	4.80	5.59	0.189	0.220
F	2.10	2.60	0.083	0.102
G	0.051	0.203	0.002	0.008
н	0.76	1.52	0.030	0.060

Ordering Information

Device	Package	Shipping
MURS360B	SMB (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

Where XXXXX is YYWWL

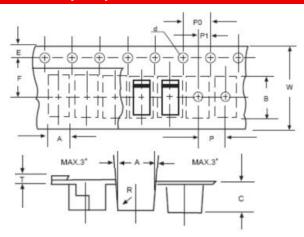


MURS = Device Type
3 = Forward Current (3A)
6 = Reverse Voltage (60V)
B = Package type
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

Carrier Tape Specification SMB



SYMBOL	Millimeters		
STWIBUL	Min.	Max.	
Α	2.97	3.17	
В	5.70	5.90	
С	2.32	2.52	
d	1.40	1.60	
E	1.40	1.60	
F	5.60	5.70	
Р	3.90	4.10	
P0	3.90	4.10	
P1	1.90	2.10	
Т	0.25	0.35	
W	11.80	12.20	

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